

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	543	438/464.ccls.	US-PGPUB; USPAT	OR	OFF	2006/03/09 09:01
L2	33	((wafer dic\$6 protective) adj tape) same (release adj tape)	US-PGPUB; USPAT	OR	ON	2006/03/09 09:43
L3	3	((wafer dic\$6 protective) adj tape) and (release adj tape)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 09:45
L4	70	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584. ccls.) and (dbg (dic\$6 near2 grind\$6))	US-PGPUB; USPAT	OR	ON	2006/03/09 09:46
L5	14	"6297131".URPN.	USPAT	OR	OFF	2006/03/09 10:04
L6	45	"5480842".URPN.	USPAT	OR	OFF	2006/03/09 10:07
L7	141	((dbg (dic\$6 near2 grind\$6))) and (semiconductor wafer package chip ic integrated die dice silicon tape)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 10:09
L8	207	((438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584. ccls.) and ((wafer dic\$6 protect\$6 releas\$6) adj tape)) and (((die chip) adj pad) leadframe (lead adj frame) ((uv ultraviolet) with adhe\$8))	US-PGPUB; USPAT	OR	ON	2006/03/09 10:14
L9	0	((wafer dic\$6 protect\$6 releas\$6) adj tape) same ((die chip) adj pad) same (leadframe (lead adj frame)) same (((package wiring) adj substrate) carrier module) with (solder adj ball))	US-PGPUB; USPAT	OR	ON	2006/03/09 10:40
L10	8	((wafer dic\$6 protect\$6 releas\$6) adj tape) same (((die chip) adj pad) with (leadframe (lead adj frame) (((package wiring) adj substrate) carrier) with (solder adj ball))))	US-PGPUB; USPAT	OR	ON	2006/03/09 10:41
L11	2	((die chip) adj pad) same (leadframe (lead adj frame)) same (((package wiring) adj substrate) carrier module) with (solder adj ball))	US-PGPUB; USPAT	OR	ON	2006/03/09 10:46

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L12	0	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584. ccls.) and ((protective adj tape) with (thermal adj degradation))	US-PGPUB; USPAT	OR	ON	2006/03/09 10:46
L13	1	((protective adj tape) same (thermal adj degradation))	US-PGPUB; USPAT	OR	ON	2006/03/09 10:46
L14	1	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584. ccls.) and ((protect\$6 adj tape) with adhe\$8 with (weaken degrad\$8) with heat\$6)	US-PGPUB; USPAT	OR	ON	2006/03/09 10:47
L15	1	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584. ccls.) and ((protect\$6 adj tape) same adhe\$8 same (weaken degrad\$8) same heat\$6)	US-PGPUB; USPAT	OR	ON	2006/03/09 10:52
L16	1	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584. ccls.) and ((protect\$6 adj tape) same (adhe\$8 bond\$6) same (weaken degrad\$8) same (heat\$6 thermal\$4 temperature))	US-PGPUB; USPAT	OR	ON	2006/03/09 10:52
L17	27	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584. ccls.) and ((protect\$6 adj tape) same (adhe\$8 bond\$6) same (heat\$6 thermal\$4 temperature))	US-PGPUB; USPAT	OR	ON	2006/03/09 10:53